

09/836,182

3/20/02

FILE 'HCAPLUS' ENTERED AT 09:51:18 ON 20 MAR 2002

L1 70 S TAPE AND WATER(2A)PERMEABILITY  
L2 213 S TAPE(2A)(PORE OR POROSIT### OR POROUS####)  
L3 1 S L2 AND (WATER OR H2O OR AQ)(2A)PERMEABILITY  
L4 78 S TAPE AND (WATER OR H2O OR AQ)(2A)PERMEABILITY  
L5 77 S L4 NOT L3  
L6 18 S TAPE(4A)(WATER OR H2O OR AQ) AND TAPE(4A)PERMEABILITY

FILE 'REGISTRY' ENTERED AT 10:04:41 ON 20 MAR 2002

L7 39 S WATER/CN OR H2 O/MF

FILE 'HCAPLUS' ENTERED AT 10:05:30 ON 20 MAR 2002

L8 2331 S L7(L)PERMEABILITY  
L9 6910 S (VAPOR OR VAPOUR OR MOISTURE)(5A)PERMEABILITY  
L10 4041 S (MOIST##### OR HUMID##### OR STEAM)(5A)PERMEABILITY  
L11 6225 S L9 AND (MOIST##### OR L7 OR AQ OR STEAM OR HUMID##### OR W  
L12 676 S AQ(5A)PERMEABILITY  
L13 9191 S L8 OR (L10 OR L11 OR L12)  
L14 2693 S L13 AND (24 OR 24H OR DAY OR HOUR OR M224H  
OR M224 OR CM224##### OR FT224##### OR IN224#####)  
L15 62 S L14 AND TAPE  
L16 58 S L15 NOT L6  
L17 5 S L16 AND (CHIP OR WAFER OR SEMICOND#####  
OR IC OR ICS OR CIRCUIT### OR PCB OR BOARD OR ELECTRONIC####)  
L18 53 S L16 NOT L17  
L19 41 S L18 AND G M2  
L20 3 S L13 AND (TAB OR (TAPE(2A)BOND#### OR  
SOLDER BALL))  
L21 374 S TAPE AUTOMATED BONDING  
L22 1 S L21 AND PERMEABILITY  
L23 46 S PRINTED CIRCUIT BOARDS AND PERMEABILITY  
L24 20 S L23 AND (MOIST##### OR L7 OR AQ OR STEAM  
OR HUMID##### OR WATER OR H2O)  
L25 3 S L23 AND (SOLDER#### OR BALL)  
L26 3645 S MOUNT####(2A)(SEMICONDUCT##### OR CHIP OR  
WAFER OR PACKAG####)  
L27 1 S L26 AND L13

FILE 'INSPEC' ENTERED AT 10:46:17 ON 20 MAR 2002

E TAPE AUTOMATED/CT

E E4+ALL/CT

L28 114975 S (MICROASSEMBLING/CT OR "MANUFACTURING  
PROCESSES"/CT OR "JOINING PROCESSES"/CT OR WELDING/CT OR "LEAD  
BONDING"/CT OR PACKAGING/CT OR "TAPE AUTOMATED BONDING"/CT OR  
TAB/CT OR "THERMOCOMPRESSSION BONDING"/CT OR "THERMOSONIC  
BONDING"/CT OR "FINE-PITCH TECHNOLOGY"/CT OR "HYBRID INTEGRATED  
CIRCUITS"/CT OR "INTEGRATED CIRCUIT TECHNOLOGY"/CT OR  
"PLASTIC PACKAGING"/CT OR "PRINTED CIRCUIT MANUFACTURE"/CT OR  
"SURFACE MOUNT TECHNOLOGY"/CT OR VLSI/CT OR "LEAD BONDING"/CT  
OR PACKAGING/CT) OR (B0170J OR B2240)/CT OR BGA OR BALLGRID OR  
BALL GRID OR TAB OR AUTOMATED BONDING  
L29 1705 S MOUNT####(2A)(SEMICONDUCT##### OR CHIP OR WAFER)  
L30 114 S (L28 OR L29) AND PERMEABILITY  
L31 1 S L30 AND TAPE  
L32 42 S L30 AND (ADHER#### OR ADHES##### OR TAB  
OR FILM OR STRIP)

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FILE 'INSPEC, PIRA, RAPRA, JICST-EPLUS, COMPENDEX, CEABA-VTB, WPIX,  
JAPIO, SCISEARCH, INSPHYS' ENTERED AT 11:04:37 ON 20 MAR 2002

L35 319 S (MOIST##### OR HUMID##### OR STEAM OR AQ  
OR WATER OR H2O)(3A) PERMEABILITY AND TAPE  
L36 3 S L35 AND (BALLGRID OR BALL GRID OR TAB OR  
TAPE AUTOMAT### OR AUTOMAT### BONDING OR BGA)  
L37 194740 S (BALLGRID OR BALL GRID OR TAB OR TAPE  
AUTOMAT### OR AUTOMAT### BONDING OR BGA)  
L38 27837 S (MOIST##### OR HUMID##### OR STEAM OR AQ  
OR WATER OR H2O)(3A) PERMEABILITY  
L39 177 S L37 AND L38  
L40 177 DUP REM L39 (0 DUPLICATES REMOVED)  
L41 1003 S TAPE(3A)(PERMEAB##### OR PORE OR POROUS  
OR POROS#####)  
L42 0 S L40 AND L41  
L43 82330 S (ADHER##### OR ADHES##### OR FILM OR  
LAYER OR STRIP)(3A)(PERMEAB##### OR PORE OR POROUS OR  
POROS#####)  
L44 33 S L40 AND L43  
L45 697 S L38 AND (SEMICONDUCT##### OR CHIP OR IC  
OR ICS OR CIRCUIT## OR PCB OR PCBS OR WAFER)  
L46 167 S L45 AND (TAPE OR ADHER##### OR ADHES#####  
OR MOUNT##### OR BGA OR BALL OR BALLGRID)  
L47 32 S L46 AND (24 OR 24H OR 24HR OR DAY OR HR)  
L48 30 DUP REM L47 (2 DUPLICATES REMOVED)